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Erratum

Erratum to “Extraction of electrical mechanisms of low-dielectric constant material MSZ for interconnect applications” [Thin Solid Films 447–448 (2004) 516–523][☆]

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The publisher regrets that affiliation “a” in the above paper was printed incorrectly. Please find the correct list of affiliations above.

We sincerely regret any embarrassment caused to those concerned.

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